TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ($L^2-\pi$ -MOSV)

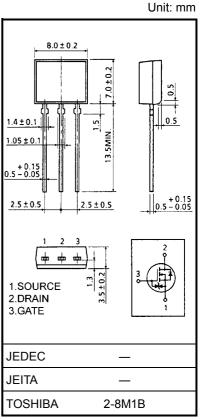
2SK2400

Chopper Regulator, DC-DC Converter and Motor Drive Applications

- 4 V gate drive
- Low drain-source ON resistance $: R_{DS} (ON) = 17 \Omega (typ.)$
- High forward transfer admittance $|Y_{fs}| = 4.5 \text{ S (typ.)}$
- Low leakage current $: I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 100 \ V)$
- Enhancement-mode $: V_{th} = 0.8 \sim 2.0 V (V_{DS} = 10 V, I_{D} = 1 mA)$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	100	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V _{DGR}	100	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC (Note 1)	۱ _D	5	А	
	Pulse (Note 1)	I _{DP}	20	А	
Drain power dissipation		PD	1.3	W	
Single pulse avalanche energy (Note 2)		E _{AS}	180	mJ	
Avalanche current		I _{AR}	5	А	
Repetitive avalanche energy (Note 3)		E _{AR}	0.13	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	



Weight: 0.54 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient	R _{th (ch−a)}	96.1	°C / W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 25 V, T_{ch} = 25°C (initial), L = 11.6 mH, R_G = 25 Ω , I_{AR} = 5 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device. Please handle with caution.

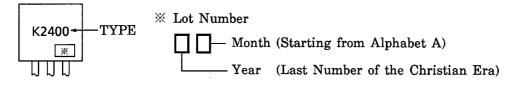
Electrical Characteristics (Ta = 25°C)

Charao	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage cu	urrent	I _{GSS}	V_{GS} = ±16 V, V_{DS} = 0 V	_	_	±10	μA	
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V	_		100	μA	
Drain−source bi voltage	reakdown	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	100	_	_	V	
Gate threshold	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	_	2.0	V	
Drain-source ON resistance		R _{DS (ON)}	V _{GS} = 4 V, I _D = 2.5 A		0.22	0.30	Ω	
			V _{GS} = 10 V, I _D = 2.5 A		0.17	0.23		
Forward transfe	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 2.5 A	2.0	4.5	_	S	
Input capacitance C_{iss} Reverse transfer capacitance C_{rss} V_{DS} = 10 V, V_{GS} = 0 V, f =				500	_			
		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	80	_	pF	
Output capacitance		C _{oss}		_	190	—		
Switching time	Rise time	tr	$V_{GS} \stackrel{10V}{}_{0V} \int \qquad I_{D} = 2.5A \\ V_{OUT} \rightarrow V_{OUT} \\ R_{L} = 20\Omega \\ V_{DD} = 50V \\ Duty \le 1\%, t_{W} = 10\mu s$	_	17	_		
	Turn-on time	t _{on}		_	25	_	20	
	Fall time	t _f		_	50	_	ns	
	Turn-off time	t _{off}		_	195	_		
Total gate charge (Gate-source plus gate-drain)		Qg		_	22	_		
Gate-source charge		Q _{gs}	V _{DD} ≈ 80 V, V _{GS} = 10 V, I _D = 5 A		15		nC	
Gate-drain ("miller") charge		Q _{gd}			7	_		

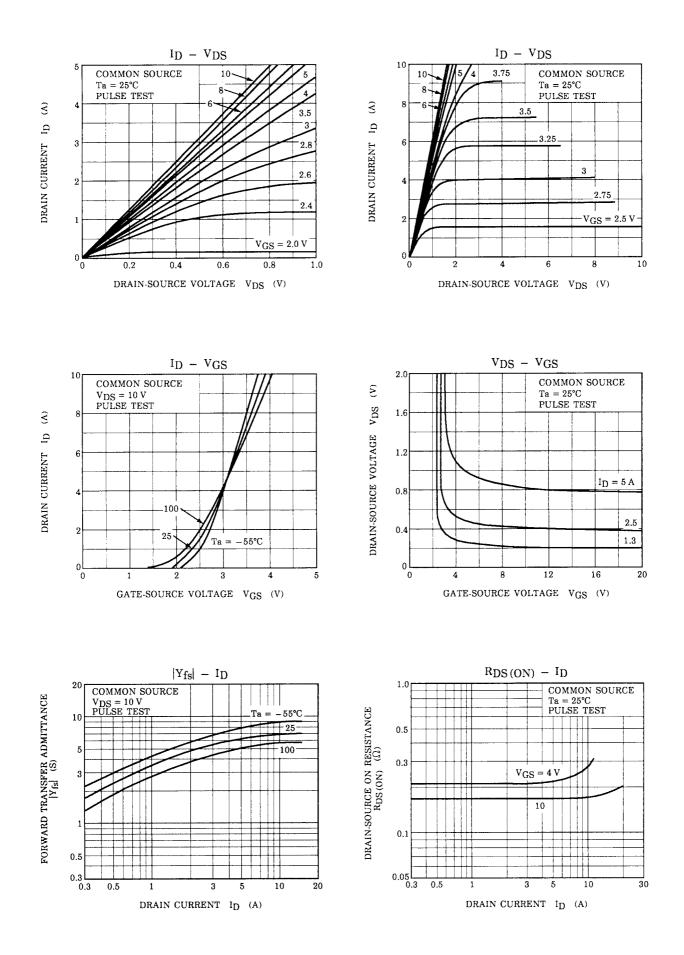
Source–Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	5	A
Pulse drain reverse current (Note 1)	I _{DRP}	—	_	_	20	A
Forward voltage (diode)	V _{DSF}	I _{DR} = 5 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 5 A, V _{GS} = 0 V, dI _{DR} / dt = 50 A / μs		160	—	ns
Reverse recovery charge	Qrr	$10R = 3 \text{ A}, \text{ VGS} = 0 \text{ V}, \text{ dIDR} / \text{ dl} = 30 \text{ A} / \text$		0.28	_	μC

Marking

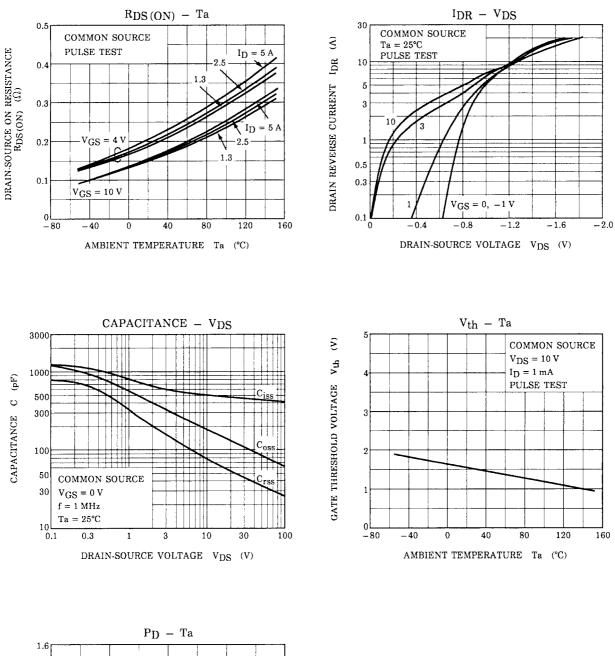


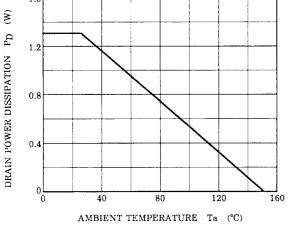
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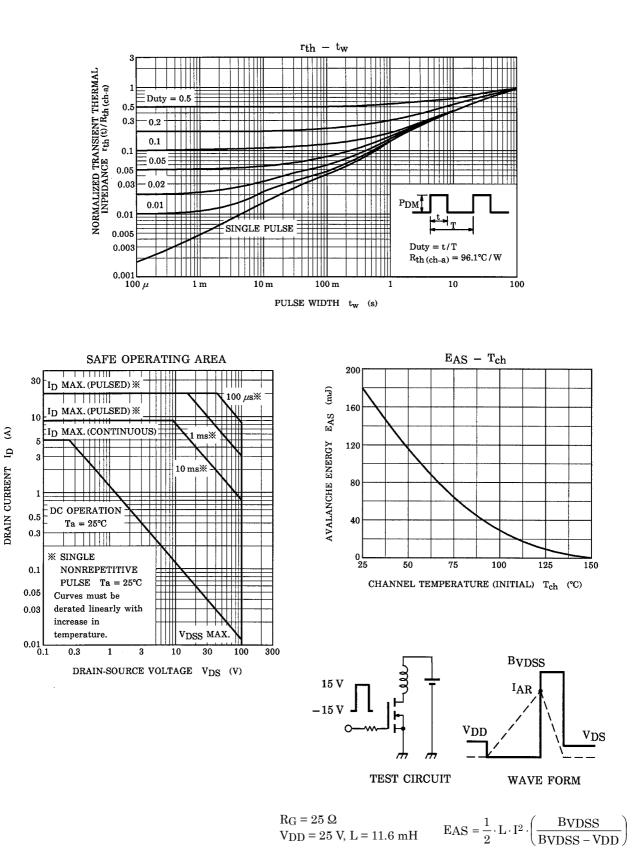
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